NEC

MOS INTEGRATED CIRCUIT

μPD42S4900, 424900

4 M-BIT DYNAMIC RAM
512 K-WORD BY 9-BIT, FAST PAGE MODE

DESCRIPTION ★

The μPD42S4900, 424900 are 524 288 words by 9 bits dynamic CMOS RAMs. The fast page mode capability realize high speed access and low power consumption.

Besides, the μPD42S4900 can execute $\overline{CAS}$ before $\overline{RAS}$ self refresh.

These are packed in 28-pin plastic TSOP and 28-pin plastic SOJ.

FEATURES

- 524 288 words by 9 bits organization
- Single +5.0 V ± 10 % power supply
- Fast access and cycle time

Part number	Power consumption Active (MAX.)	Access time (MAX.)	R/W cycle time (MIN.)	Fast page mode cycle time (MIN.)
μPD42S4900-70, 424900-70	880 mW	70 ns	130 ns	45 ns
μPD42S4900-80, 424900-80	770 mW	80 ns	150 ns	50 ns

- The μPD42S4900 can execute $\overline{CAS}$ before $\overline{RAS}$ self refresh

Part number	Refresh cycle	Refresh	Power consumption at standby (MAX.)
μPD42S4900	1 024 cycles/128 ms	$\overline{CAS}$ before $\overline{RAS}$ self refresh, $\overline{CAS}$ before $\overline{RAS}$ refresh, $\overline{RAS}$ only refresh, Hidden refresh	1.1 mW (CMOS level input)
μPD424900	1 024 cycles/ 16 ms	$\overline{CAS}$ before $\overline{RAS}$ refresh, $\overline{RAS}$ only refresh, Hidden refresh	5.5 mW (CMOS level input)

- Multiplexed address inputs ..... Row address: A0 to A9, Column address: A0 to A8

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The mark ★ shows revised points.

★ ORDERING INFORMATION

Part number	Access time (MAX.)	Package	Refresh
μPD42S4900G5-70-7JD	70 ns	28-pin Plastic TSOP (400 mil)	$\overline{CAS}$ before $\overline{RAS}$ self refresh $\overline{RAS}$ only refresh $\overline{CAS}$ before $\overline{RAS}$ refresh Hidden refresh
μPD42S4900G5-80-7JD	80 ns		
μPD42S4900G5-70-7KD	70 ns	28-pin Plastic TSOP (Reverse bent) (400 mil)	
μPD42S4900G5-80-7KD	80 ns		
μPD42S4900LE-70	70 ns	28-pin Plastic SOJ (400 mil)	
μPD42S4900LE-80	80 ns		
μPD424900G5-70-7JD	70 ns	28-pin Plastic TSOP (400 mil)	$\overline{RAS}$ only refresh $\overline{CAS}$ before $\overline{RAS}$ refresh Hidden refresh
μPD424900G5-80-7JD	80 ns		
μPD424900G5-70-7KD	70 ns	28-pin Plastic TSOP (Reverse bent) (400 mil)	
μPD424900G5-80-7KD	80 ns		
μPD424900LE-70	70 ns	28-pin Plastic SOJ (400 mil)	
μPD424900LE-80	80 ns		

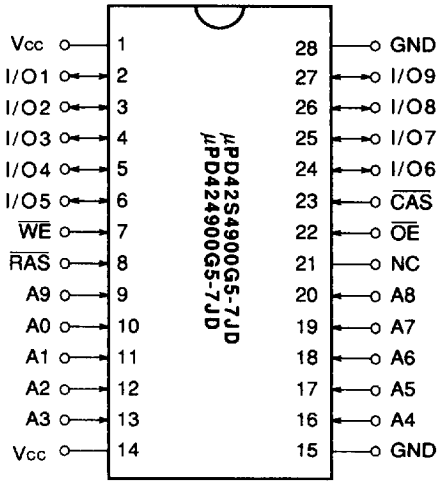
QUALITY GRADE

STANDARD

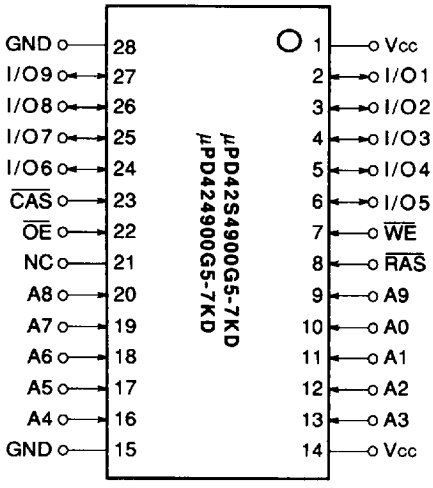
Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

PIN CONFIGURATIONS (Marking side) ★

28-pin Plastic TSOP (400 mil)

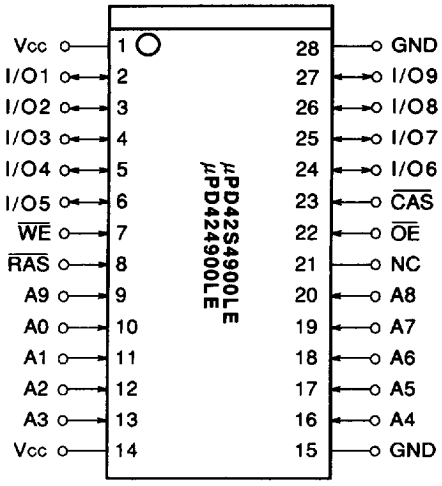


28-pin Plastic TSOP (Reverse bent) (400 mil)



A0 to A9	: Address Inputs
I/O1 to I/O9	: Data Inputs/Outputs
$\overline{RAS}$	: Row Address Strobe
$\overline{CAS}$	: Column Address Strobe
$\overline{WE}$	: Write Enable
$\overline{OE}$	: Output Enable
Vcc	: Supply Voltage
GND	: Ground
NC	: No Connection

28-pin Plastic SOJ
(400 mil)



A0 to A9	: Address Inputs
I/O1 to I/O9	: Data Inputs/Outputs
$\overline{RAS}$	: Row Address Strobe
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$\overline{WE}$	: Write Enable
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Vcc	: Supply Voltage
GND	: Ground
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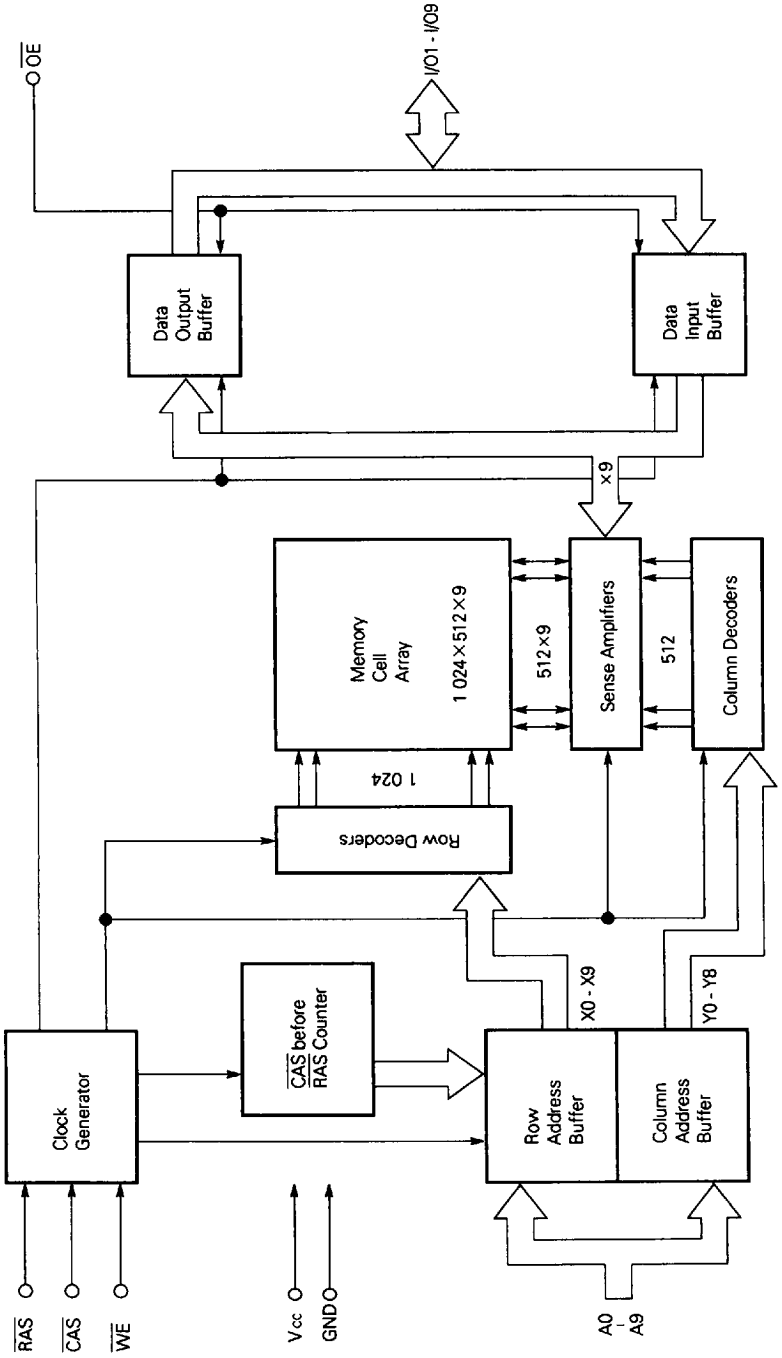
BLOCK DIAGRAM ★



★ INPUT/OUTPUT PIN FUNCTIONS

The μPD42S4900, 424900 have input pins $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$, A0 to A9 and input/output pins I/O1 to I/O9.

Pin name	Input/ Output	Function
$\overline{RAS}$ (Row address strobe)	Input	$\overline{RAS}$ activates the sense amplifier by latching a row address (A0 to A9) and selecting a corresponding word line. It refreshes memory cell array of one line (4 608-bit) selected by the row address (A0 to A9). It also selects the following function. • $\overline{CAS}$ before $\overline{RAS}$ refresh.
$\overline{CAS}$ (Column address strobe)	Input	$\overline{CAS}$ activates data input/output circuit by latching column address (A0 to A8) and selecting a digit line connected with the sense amplifier.
A0 to A9 (Address input)	Input	10-bit address bus. Input total 19-bit of address signal, upper 10-bit and lower 9-bit in sequence (address multiplex method). Therefore, one word (9-bit) is selected from 524 288-word by 9-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{RAS}$. Then, switch the address bus to column address and activate $\overline{CAS}$. Each address is taken into the device when $\overline{RAS}$ and $\overline{CAS}$ are activated. Therefore, the address input setup time (t_{ASR}, t_{ASC}) and hold time (t_{RAH}, t_{CAH}) are specified for the activation of $\overline{RAS}$ and $\overline{CAS}$.
$\overline{WE}$ (Write enable)	Input	Write control signal. Write operation is executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{WE}$.
$\overline{OE}$ (Output enable)	Input	Read control signal. Read operation can be executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{OE}$. If $\overline{WE}$ is activated during read operation, $\overline{OE}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O9 (Data input/output)	Input/ Output	9-bit data bus. I/O1 to I/O9 are used to input/output data.

ELECTRICAL SPECIFICATIONS Notes 1, 2

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Voltage on Any Pin Relative to GND	V_T		−1.0 to +7.0	V
Supply Voltage	V_{CC}		−1.0 to +7.0	V
Output Current	I_O		50	mA
Power Dissipation	P_D		1	W
Operating Temperature	T_{opt}		0 to +70	°C
Storage Temperature	T_{stg}		−55 to +125	°C

Remark Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V_{CC}		4.5	5.0	5.5	V
High Level Input Voltage	V_{IH}		2.4		V_{CC} +1.0	V
Low Level Input Voltage	V_{IL}		−1.0		+0.8	V
Ambient Temperature	T_a		0		70	°C

CAPACITANCE (T_a = +25 °C, f = 1 MHz)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input Capacitance	C_{I1}	A0 to A9			5	pF
	C_{I2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$			7	pF
Data Input/Output Capacitance	C_D	I/O1 to I/O9			7	pF

DC CHARACTERISTICS (Recommended Operating Conditions unless otherwise noted)

Parameter		Symbol	Test condition		MIN.	MAX.	Unit	Notes
Operating current		I_{CC1}	$\overline{RAS}$, $\overline{CAS}$ Cycling $t_{RC} = t_{RC(MIN)}$, I_O = 0 mA	t_{RAC} = 70 ns		160	mA	3, 4
				t_{RAC} = 80 ns		140		
Standby current	μPD42S4900	I_{CC2}	$V_{IH(MIN)} \leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		2	mA	
			V_{CC}–0.2 V $\leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		0.15		
	μPD424900		$V_{IH(MIN)} \leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		2		
			V_{CC}–0.2 V $\leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		1		
$\overline{RAS}$ only refresh current		I_{CC3}	$\overline{RAS}$ Cycling, $V_{IH(MIN)} \leqq \overline{CAS}$ $t_{RC} = t_{RC(MIN)}$, I_O = 0 mA	t_{RAC} = 70 ns		160	mA	3, 4
				t_{RAC} = 80 ns		140		
Operating current (Fast page mode)		I_{CC4}	$\overline{RAS} \leqq V_{IL(MAX)}$ $\overline{CAS}$ Cycling, $t_{PC} = t_{PC(MIN)}$, I_O = 0 mA	t_{RAC} = 70 ns		150	mA	3, 4
				t_{RAC} = 80 ns		130		
$\overline{CAS}$ before $\overline{RAS}$ refresh current		I_{CC5}	$\overline{RAS}$ Cycling, $t_{RC} = t_{RC(MIN)}$, I_O = 0 mA	t_{RAC} = 70 ns		160	mA	3, 4
				t_{RAC} = 80 ns		140		
$\overline{CAS}$ before $\overline{RAS}$ long refresh current (1 024 cycles/128 ms, only for μPD42S4900)		I_{CC6}	Standby : $\overline{RAS}$, $\overline{CAS}$: V_{CC}–0.2 V $\leqq V_{IH} \leqq V_{IH(MAX)}$ $\overline{CAS}$ before $\overline{RAS}$ refresh : 1 024 cycles/128 ms $\overline{RAS}$, $\overline{CAS}$: 0 V $\leqq V_{IL} \leqq$ 0.2 V V_{CC}–0.2 V $\leqq V_{IH} \leqq V_{IH(MAX)}$ $\overline{OE}$: V_{IH} Address input, $\overline{WE}$: V_{IH} or V_{IL} Output : Hi-Z	$t_{RAS} \leqq$ 200 ns		200	μA	3, 4
				$t_{RAS} \leqq$ 1 μs		300		
Self refresh current ($\overline{CAS}$ before $\overline{RAS}$ self refresh, only for μPD42S4900)		I_{CC7}	I_O = 0 mA $\overline{RAS}$, $\overline{CAS}$: 0 V $\leqq V_{IL} \leqq$ 0.2 V V_{CC}–0.2 V $\leqq V_{IH} \leqq V_{IH(MAX)}$			150	μA	
Input leakage current		$I_{I(L)}$	V_I = 0 to 5.5 V all other pins except for testing pin = 0 V		–10	+10	μA	
Output leakage current		$I_{O(L)}$	Output is disabled (Hi-Z) V_O = 0 to 5.5 V		–10	+10	μA	
High level output voltage		V_{OH}	I_O = –5.0 mA		2.4		V	
Low level output voltage		V_{OL}	I_O = 4.2 mA			0.4	V	

AC CHARACTERISTICS

(Recommended Operating Conditions unless otherwise noted) Notes 6, 7 (1/2)

Parameter	Symbol	t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.		
Random Read or Write Cycle Time	t_{RC}	130		150		ns	7
Read Modify Write Cycle Time	t_{RWC}	180		205		ns	7
Fast Page Mode Cycle Time	t_{PC}	45		50		ns	7
Read Modify Write Cycle Time (Fast Page Mode)	t_{PRWC}	95		105		ns	7
Access Time from $\overline{RAS}$	t_{RAC}		70		80	ns	8, 9
Access Time from $\overline{CAS}$	t_{CAC}		20		20	ns	8, 9
Access Time from Column Address	t_{AA}		35		40	ns	8, 9
Access Time from $\overline{CAS}$ Precharge	t_{ACP}		40		45	ns	9
$\overline{CAS}$ to Output Data Setup Time	t_{CLZ}	0		0		ns	9
Output Buffer Turn-off Delay Time ($\overline{CAS}$)	t_{OFF}	0	15	0	20	ns	10
Transition Time (rise and fall)	t_T	3	50	3	50	ns	
$\overline{RAS}$ Precharge Time	t_{RP}	50		60		ns	
$\overline{RAS}$ Pulse Width	t_{RAS}	70	10 000	80	10 000	ns	
$\overline{RAS}$ Pulse Width (Fast Page Mode)	t_{RASP}	70	125 000	80	125 000	ns	
$\overline{RAS}$ Hold Time	t_{RSH}	20		20		ns	
$\overline{CAS}$ Hold Time	t_{CSH}	70		80		ns	
$\overline{CAS}$ Pulse Width	t_{CAS}	20	10 000	20	10 000	ns	
$\overline{RAS}$ to $\overline{CAS}$ Delay Time	t_{RCD}	20	50	20	60	ns	8
$\overline{RAS}$ to Column Address Delay Time	t_{RAD}	15	35	15	40	ns	8
$\overline{CAS}$ to $\overline{RAS}$ Precharge Time	t_{CRP}	10		10		ns	11
$\overline{CAS}$ Precharge Time (Fast Page Mode)	t_{CP}	10		10		ns	
Row Address Setup Time	t_{ASR}	0		0		ns	
Row Address Hold Time	t_{RAH}	10		10		ns	
Column Address Setup Time	t_{ASC}	0		0		ns	
Column Address Hold Time	t_{CAH}	15		15		ns	
$\overline{CAS}$ Precharge Time	t_{CPN}	10		10		ns	
Column Address Lead Time Referenced to $\overline{RAS}$	t_{RAL}	35		40		ns	
Read Command Setup Time	t_{RCS}	0		0		ns	
Read Command Hold Time Referenced to $\overline{CAS}$	t_{RCH}	0		0		ns	12
Read Command Hold Time Referenced to $\overline{RAS}$	t_{RRH}	0		0		ns	12
Write Command Hold Time Referenced to $\overline{CAS}$	t_{WCH}	15		15		ns	13
Write Command Pulse Width	t_{WP}	15		15		ns	13
Write Command Lead Time Referenced to $\overline{RAS}$	t_{RWL}	20		20		ns	
Write Command Lead Time Referenced to $\overline{CAS}$	t_{CWL}	20		20		ns	
Data-in Setup Time	t_{DS}	0		0		ns	14
Data-in Hold Time	t_{DH}	15		15		ns	14

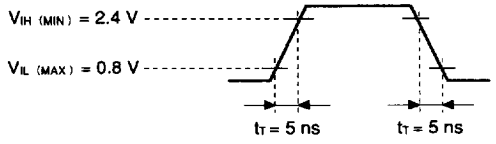
(2/2)

Parameter		Symbol	tRAC = 70 ns		tRAC = 80 ns		Unit	Notes
			MIN.	MAX.	MIN.	MAX.		
Refresh Time	μPD42S4900	tREF		128		128	ms	16
	μPD424900			16		16	ms	
Write Command Setup Time		tWCS	0		0		ns	15
$\overline{CAS}$ to $\overline{WE}$ Delay Time		tCWD	45		50		ns	15
$\overline{RAS}$ to $\overline{WE}$ Delay Time		tRWD	95		110		ns	15
$\overline{CAS}$ Precharge Delay Time Referenced to $\overline{WE}$ (Fast Page Mode)		tCPWD	65		75		ns	15
Column Address Delay Time Referenced to $\overline{WE}$		tAWD	60		70		ns	15
$\overline{CAS}$ Setup Time ($\overline{CAS}$ before $\overline{RAS}$ Refresh)		tCSR	10		10		ns	
★ $\overline{CAS}$ Hold Time ($\overline{CAS}$ before $\overline{RAS}$ Refresh)		tCHR	10		10		ns	
$\overline{RAS}$ Precharge to $\overline{CAS}$ Hold Time		tRPC	10		10		ns	
$\overline{OE}$ to $\overline{RAS}$ inactive Setup Time		tOES	0		0		ns	
Access Time from $\overline{OE}$		tOEA		20		20	ns	9
$\overline{OE}$ Data Delay Time		tOED	15		20		ns	
Output Buffer Turn-off Delay Time ($\overline{OE}$)		tOEZ	0	15	0	20	ns	10
$\overline{OE}$ Output Data Setup Time		tOLZ	0		0		ns	
$\overline{OE}$ Hold Time		tOEH	0		0		ns	
$\overline{RAS}$ Hold Time Referenced to $\overline{CAS}$ Precharge		tRHCP	40		45		ns	
$\overline{RAS}$ Pulse Width ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh)		tRASS	100		100		μs	16
$\overline{CAS}$ Pulse Width ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh)		tCASS	500		500		μs	16
$\overline{RAS}$ Precharge Time ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh)		tRPS	130		150		ns	16
$\overline{CAS}$ Hold Time ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh)		tCHS	–50		–50		ns	16

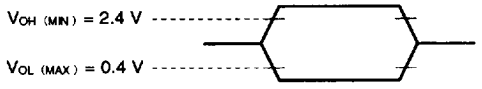
Notes

1. All voltages are referenced to GND.
2. An initial pause of 100 μs is required after power up followed by 8 $\overline{RAS}$ only refresh cycles before proper device operation is achieved. In case of using internal address refresh counter, a minimum of 8 $\overline{CAS}$ before $\overline{RAS}$ refresh cycles instead of 8 $\overline{RAS}$ only refresh cycles are required.
3. I_{CC1}, I_{CC3}, I_{CC4}, I_{CC5}, and I_{CC6} depend on t_{RC} and t_{PC} Specified values are obtained with outputs open.
4. Address can be changed once or less while $\overline{RAS}$ = V_{IL} and $\overline{CAS}$ = V_{IH}.
5. AC measurements assume t_T = 5 ns.
6. AC Characteristics test condition

(1) Input timing specification



(2) Output timing specification



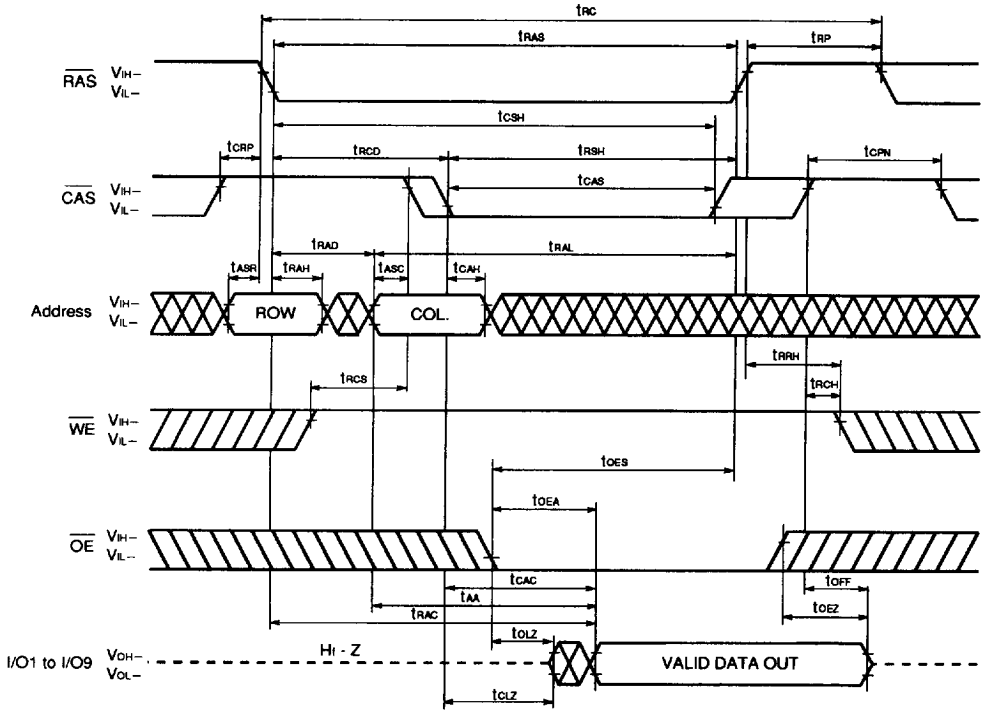
7. The minimum specifications are used only to indicate cycle time at which proper operation over the full temperature range (T_a = 0 to 70 °C) is assured.
8. In random read cycle, the access time is changed by the conditions of t_{RAD} and t_{RCD} as follows.

Condition	Access time
$t_{RAD} \leq t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{RAC\ (MAX)}$
$t_{RAD\ (MAX.)} \leq t_{RAD}$ and $t_{RCD} \leq t_{RCD\ (MAX)}$	$t_{AA\ (MAX.)}$
$t_{RCD\ (MAX.)} \leq t_{RCD}$	$t_{CAC\ (MAX)}$

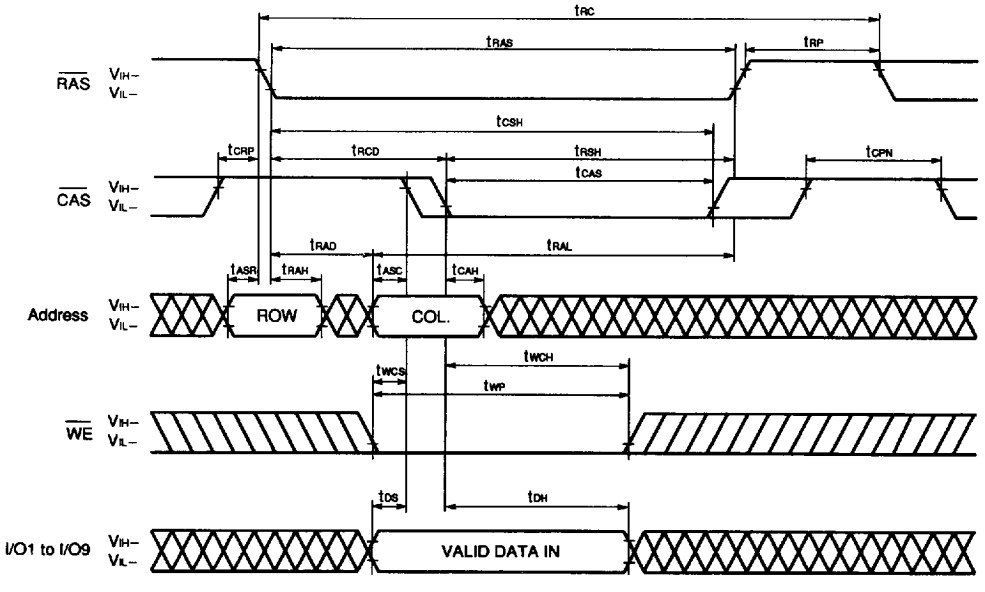
$t_{RAD\ (MAX)}$ and $t_{RCD\ (MAX)}$ indicate the points which the access time changes and are not the limits of operation.

9. Loading conditions are 2 TTL and 100 pF.
10. $t_{OFF\ (MAX)}$ and $t_{OEZ\ (MAX)}$ define the time at which the output achieves the open circuit condition and are not referenced to V_{OH} or V_{OL}.
11. $t_{CRP\ (MIN.)}$ requirement should be applicable for $\overline{RAS}$ / $\overline{CAS}$ cycles preceded by any cycles.
12. Either $t_{RCH\ (MIN)}$ or $t_{RRH\ (MIN)}$ must be satisfied for a read cycle.
13. $t_{WP\ (MIN.)}$ is applicable for late write cycle or read modify write cycle. In early write cycles, $t_{WCH\ (MIN)}$ should be satisfied.
14. This specification is referenced to $\overline{CAS}$ falling edge in early write cycles and to $\overline{WE}$ falling edge in late write or read modify write cycles.
15. t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{WCS\ (MIN)} \leq t_{WCS}$, the cycle is an early write cycle and the data out pins will remain Hi-Z through the entire cycle. If $t_{RWD\ (MIN.)} \leq t_{RWD}$, $t_{CWD\ (MIN)} \leq t_{CWD}$, $t_{AWD\ (MIN.)} \leq t_{AWD}$ and $t_{CPWD\ (MIN.)} \leq t_{CPWD}$, the cycle is a read modify write cycle and condition of the data out (at access time) is indeterminate.
16. This specification is applicable only for μPD42S4900.

READ CYCLE

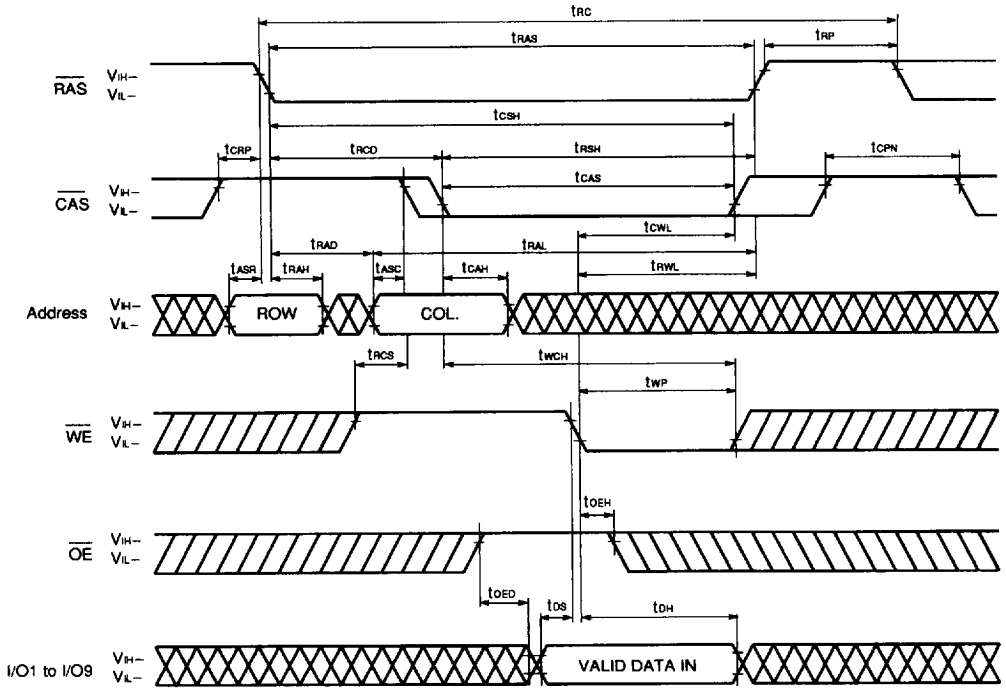


EARLY WRITE CYCLE

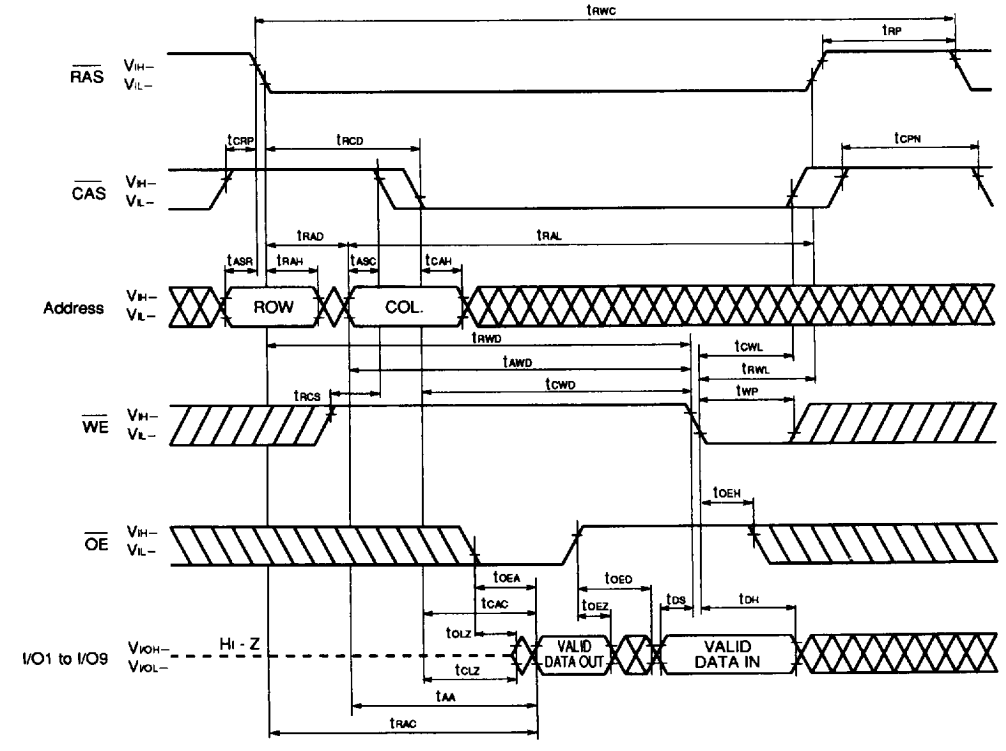


Remark $\overline{OE}$ = Don't Care

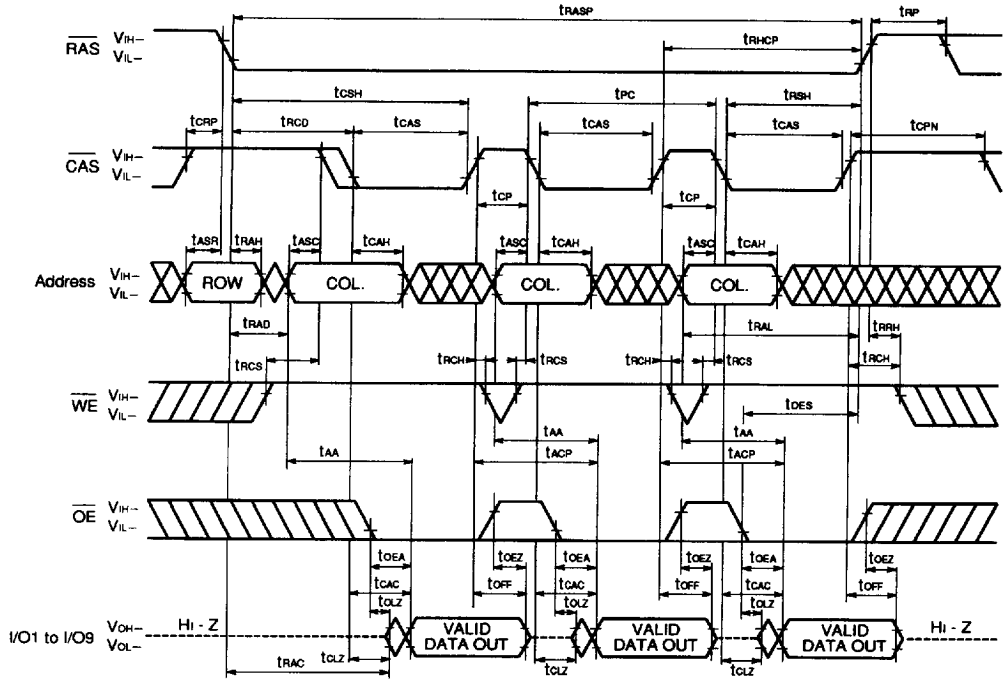
LATE WRITE CYCLE



READ MODIFY WRITE CYCLE

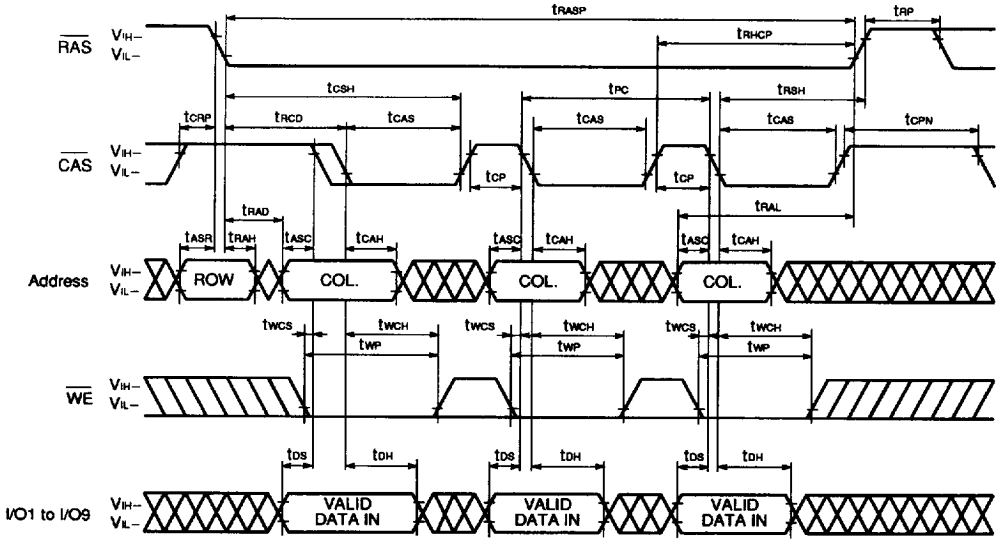


FAST PAGE MODE READ CYCLE



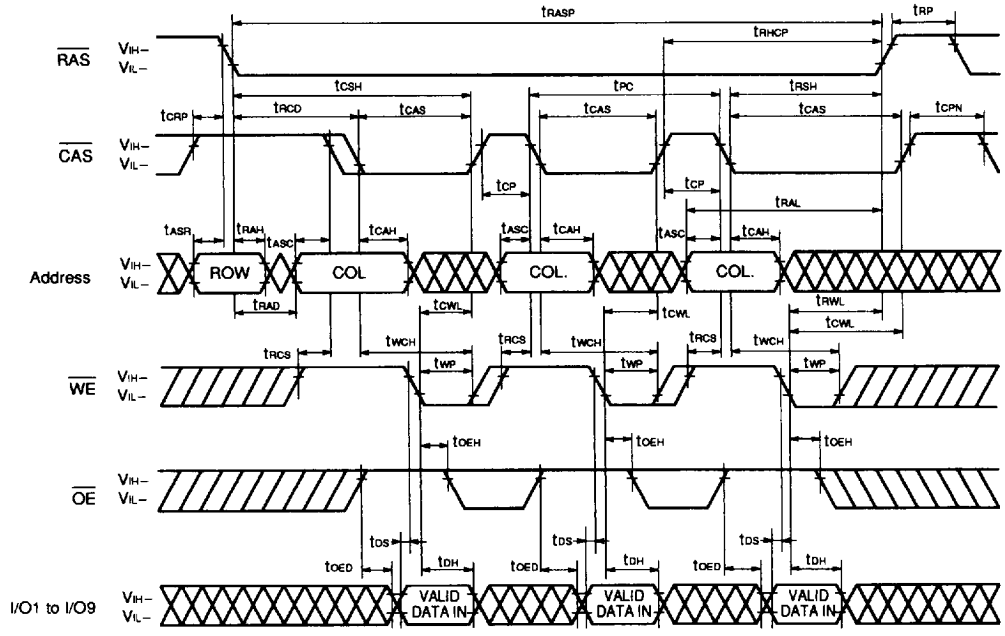
Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

FAST PAGE MODE EARLY WRITE CYCLE



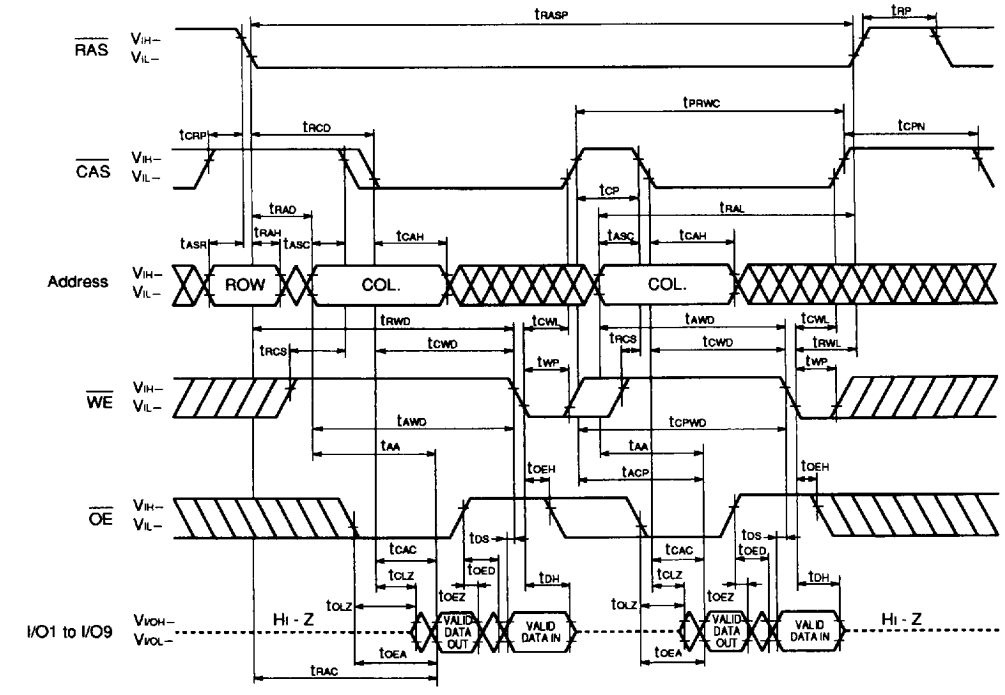
Remark $\overline{OE}$ = Don't Care
In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

FAST PAGE MODE LATE WRITE CYCLE



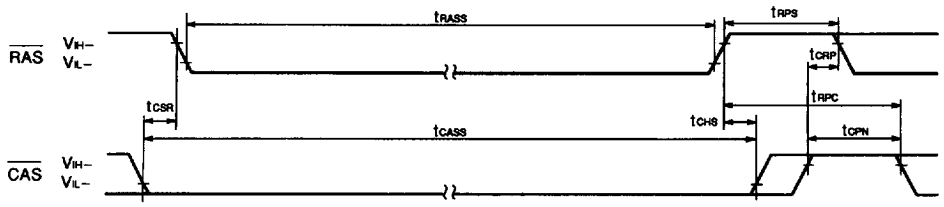
Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

FAST PAGE MODE READ MODIFY WRITE CYCLE



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

★ $\overline{CAS}$ BEFORE $\overline{RAS}$ SELF REFRESH CYCLE (Only for μPD42S4900)



Remark Address, $\overline{WE}$, $\overline{OE}$ = Don't care I/O1 to I/O9 = HI - Z

How to use $\overline{CAS}$ before $\overline{RAS}$ self refresh mode.

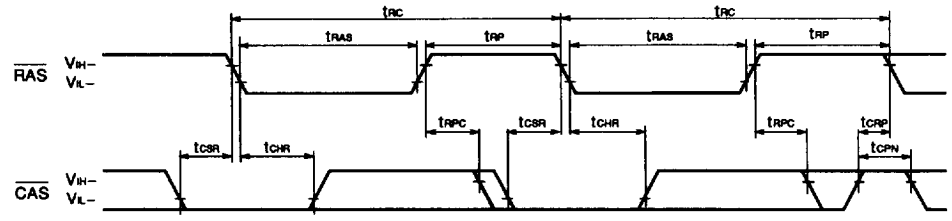
$\overline{CAS}$ before $\overline{RAS}$ self refresh mode can't be used by itself. It must be used with perfoming one of 3 refreshes below.

- **When using distributed $\overline{CAS}$ before $\overline{RAS}$ refresh**
  Refresh 1 024 times during 128 ms before set into the $\overline{CAS}$ before $\overline{RAS}$ self refresh mode and after reset.

- **When using burst $\overline{CAS}$ before $\overline{RAS}$ refresh**
  Refresh 1 024 times during 16 ms before set into the $\overline{CAS}$ before $\overline{RAS}$ self refresh mode and after reset.

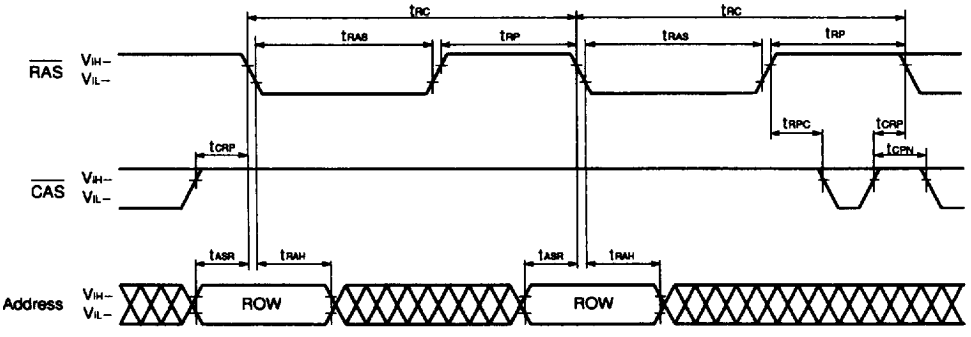
- **When using $\overline{RAS}$ only refresh**
  Refresh against all refresh addresses during 16 ms before set into the $\overline{CAS}$ before $\overline{RAS}$ self refresh mode and after reset.

$\overline{CAS}$ BEFORE $\overline{RAS}$ HIDDEN REFRESH CYCLE ★



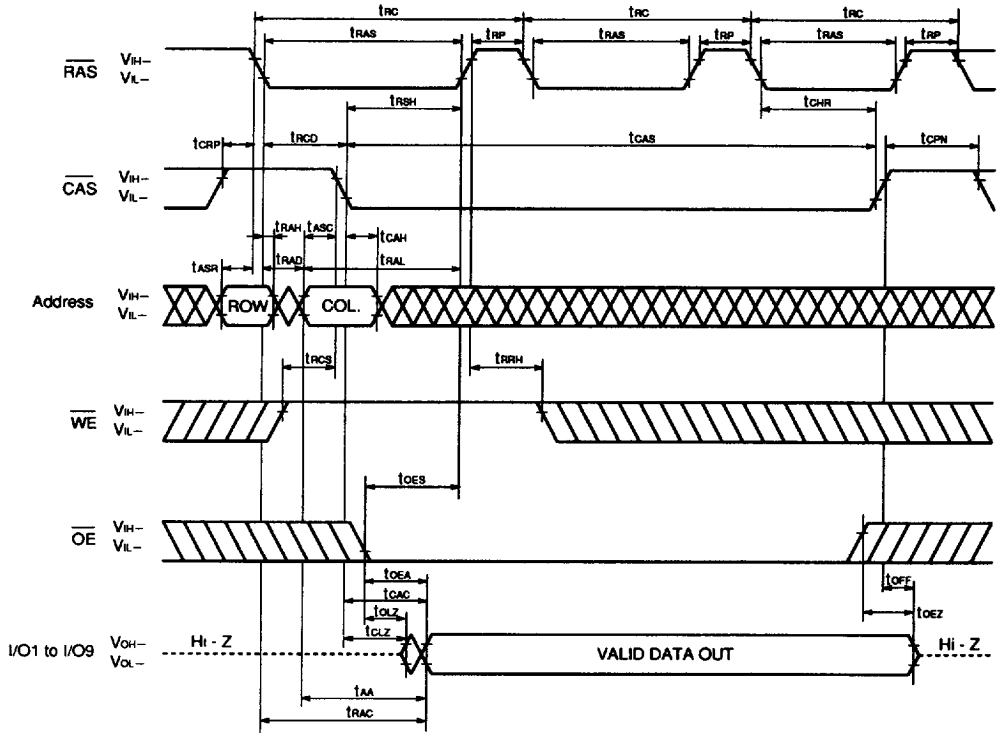
Remark Address, $\overline{WE}$, $\overline{OE}$ = Don't care I/O1 to I/O9 = Hi - Z

$\overline{RAS}$ ONLY REFRESH CYCLE ★



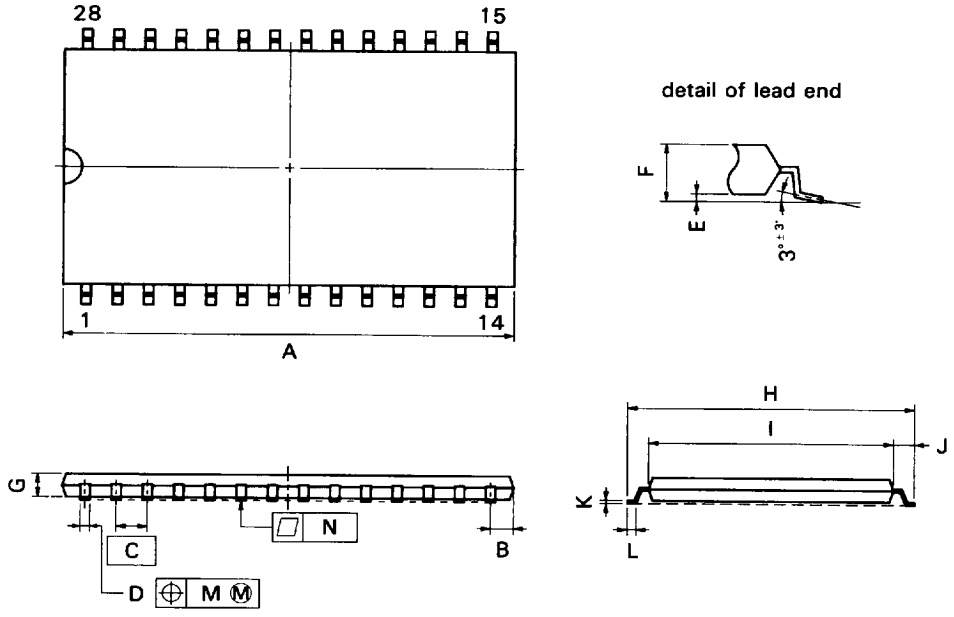
Remark $\overline{WE}$, $\overline{OE}$ = Don't care I/O1 to I/O9 = Hi - Z

HIDDEN REFRESH CYCLE



★ **PACKAGE DRAWINGS**

28 PIN PLASTIC TSOP (400mil)

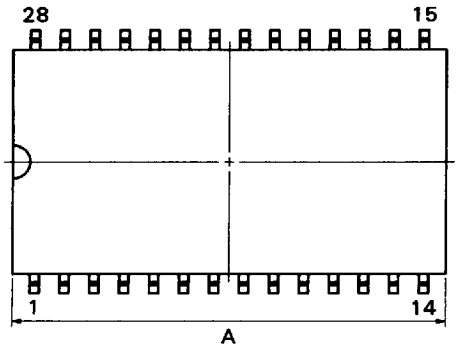


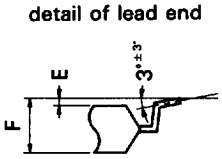
S28G5 50-7JD 1

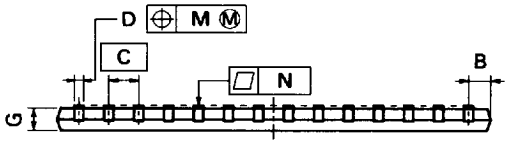
NOTE
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

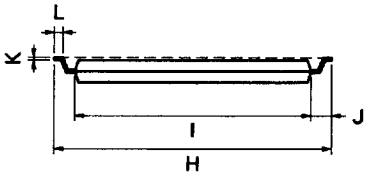
ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.40^{\pm 0.10}$	$0.016^{+0.004}_{-0.005}$
E	$0.05^{\pm 0.05}$	$0.002^{\pm 0.002}$
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	$11.76^{\pm 0.2}$	$0.463^{\pm 0.008}$
I	$10.16^{\pm 0.1}$	$0.400^{\pm 0.004}$
J	$0.8^{\pm 0.2}$	$0.031^{+0.008}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	$0.5^{\pm 0.1}$	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC TSOP (400mil)









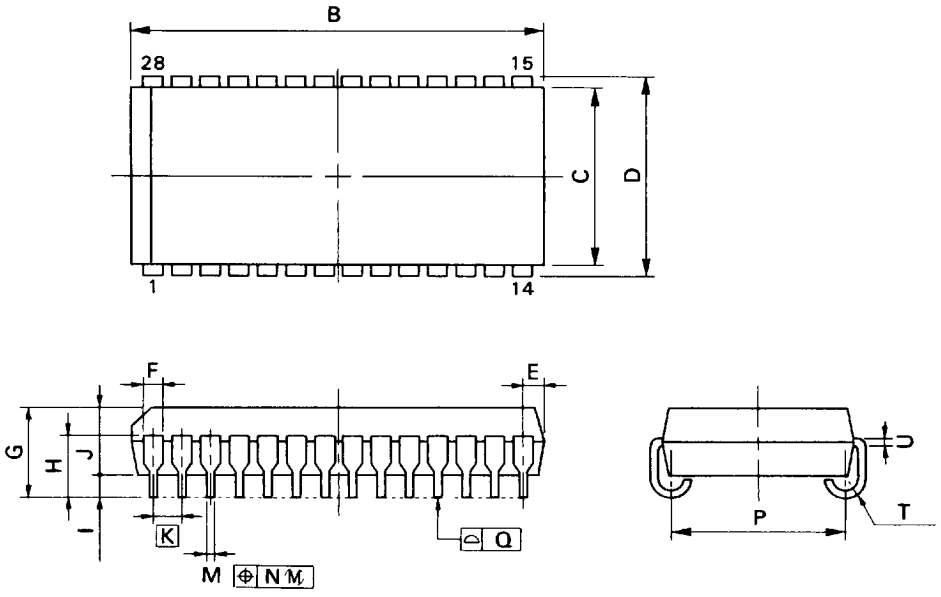
S28G5-50-7KD-1

NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.40^{\pm 0.10}$	$0.016^{+0.004}_{-0.005}$
E	$0.05^{\pm 0.05}$	$0.002^{\pm 0.002}$
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	$11.76^{\pm 0.2}$	$0.463^{\pm 0.008}$
I	$10.16^{\pm 0.1}$	$0.400^{\pm 0.004}$
J	$0.8^{\pm 0.2}$	$0.031^{+0.008}_{-0.009}$
K	$0.125^{+0.10}_{-0.08}$	$0.005^{+0.004}_{-0.002}$
L	$0.5^{\pm 0.1}$	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

28PIN PLASTIC SOJ (400 mil)



P28LA-400A 1

NOTE

Each lead centerline is located within 0 12 mm (0 005 inch) of its true position (T P) at maximum material condition

ITEM	MILLIMETERS	INCHES
B	$18.67^{+0.2}_{-0.35}$	$0.735^{+0.008}_{-0.013}$
C	10.16	0.400
D	$11.18^{\pm 0.2}$	$0.440^{+0.008}_{-0.009}$
E	$1.08^{\pm 0.15}$	$0.043^{+0.006}_{-0.009}$
F	0.6	0.024
G	$3.5^{\pm 0.2}$	$0.138^{+0.008}_{-0.009}$
H	$2.4^{\pm 0.2}$	$0.094^{+0.008}_{-0.009}$
I	0.8 MIN	0.031 MIN
J	2.6	0.102
K	1.27 (T P)	0.050 (T P)
M	$0.40^{\pm 0.10}$	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	$9.40^{\pm 0.20}$	$0.370^{+0.008}_{-0.009}$
Q	0.15	0.006
T	R0.85	R0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

★ RECOMMENDED SOLDERING CONDITIONS

Please consult with our sales offices for soldering conditions of the μPD42S4900, 424900.

TYPE OF SURFACE MOUNT DEVICE

μPD42S4900G5, 424900G5 : 28-pin Plastic TSOP (400 mil)
μPD42S4900LE, 424900LE : 28-pin Plastic SOJ (400 mil)